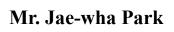


Korean International Semiconductor Conference & Exhibition on Manufacturing Technology 2025

## KISM 2025 BUSAN

Re:Innovation of Semiconductor Manufacturing for AI Ecosystem



(Samsung Electronics)



Jae-wha Park worked at Samsung Electronics Semiconductor RnD Center for 22 years and is currently in charge of developing HBM and 3D-IC using HCB (Hybrid Cu bonding). His main areas of development include TSV, Cu Pad, wafer&chip warpage control, HCB bonding, and Carrier processes.